

AMENDMENTS TO THE CLAIMS

Please amend the Claim Form and Claims as follows. Insertions are shown underlined while deletions are ~~struck through~~. Please cancel claims 1, 2 and 5.

1 (canceled);

2 (canceled);

3 (currently amended): A dummy wafer comprising a carbon fiber reinforced plastic, having a wafer substrate including a carbon fiber reinforced plastic~~The dummy wafer according to claim 2,~~ wherein said carbon fiber reinforced plastic includes carbon fibers having a tensile modulus of 400 GPa or higher.

4 (original): The dummy wafer according to claim 3, wherein said carbon fibers are pitch-based carbon fibers.

5 (canceled);

6 (currently amended): The dummy wafer comprising a carbon fiber reinforced plastic, having a wafer substrate including a carbon fiber reinforced plastic, wherein said wafer substrate has a plurality of CFRP layers which are layers consisting of a carbon fiber reinforced plastic~~The dummy wafer according to claim 5,~~ wherein said wafer substrate has a plurality of one-dimensionally reinforced CFRP layers, said one-dimensionally reinforced CFRP layer being a layer consisting of a carbon fiber reinforced plastic consisting of a cured and shaped product of a unidirectional prepreg in which carbon fibers are oriented in one direction, and

the tensile modulus of the carbon fibers in a part of layers among said plurality of one-dimensionally reinforced CFRP layers is higher than the tensile modulus of the carbon fiber in the other layers.

7 (original): The dummy wafer according to claim 6, wherein
said wafer substrate has two skin layers each located on principal surface side, and a core layer located between said two skin layers;

both of said two skin layers have a plurality of said one-dimensionally reinforced CFRP layers;

when the orientation direction of carbon fibers in one of the two outermost CFRP layers, which are one-dimensionally reinforced CFRP layers located closest to the principal surface side in each of said two skin layers, is made to be a reference direction, the orientation direction of

carbon fibers in the other outermost CFRP layer falls within an angle range from -20° to $+20^{\circ}$ with respect to the reference direction;

the tensile modulus of carbon fibers in both the two outermost CFRP layers is 200 GPa to 600 GPa;

both the two skin layers have a one-dimensionally reinforced CFRP layer containing carbon fibers oriented in an angle range from $+75^{\circ}$ to $+90^{\circ}$ with respect to the reference direction and having a tensile modulus of 400 GPa to 1000 GPa and higher than the tensile modulus of carbon fibers in either outermost CFRP layer and/or a one-dimensionally reinforced CFRP layer containing carbon fibers oriented in an angle range from -75° to -90° with respect to the reference direction and having a tensile modulus of 400 GPa to 1000 GPa and higher than the tensile modulus of carbon fibers in either outermost CFRP layer; and

said core layer has a one-dimensionally reinforced CFRP layer containing carbon fibers oriented in an angle range from $+30^{\circ}$ to $+60^{\circ}$ with respect to the reference direction and having a tensile modulus of 400 GPa to 1000 GPa, and/or a one-dimensionally reinforced CFRP layer containing carbon fibers oriented in an angle range from -30° to -60° and having a tensile modulus of 400 GPa to 1000 GPa.

8 (original): The dummy wafer according to claim 7, wherein the thickness of each of said two skin layers is 10% to 45% the total thickness of said two skin layers and the core layer.

9 (original): A dummy wafer comprising a wafer substrate including a carbon fiber reinforced plastic, wherein

said wafer substrate has two skin layers each located on principal surface side, and a core layer located between said two skin layers;

both of said two skin layers have a plurality of one-dimensionally reinforced CFRP layers, said one-dimensionally reinforced CFRP layer being a layer consisting of a carbon fiber reinforced plastic consisting of a cured and shaped product of a unidirectional prepreg in which carbon fibers are oriented in one direction;

when the orientation direction of carbon fibers in one of the two outermost CFRP layers, which are one-dimensionally reinforced CFRP layers located closest to the principal surface side in each of said two skin layers, is made to be a reference direction, the orientation direction of

carbon fibers in the other outermost CFRP layer falls within an angle range from -20° to $+20^{\circ}$ with respect to the reference direction;

the tensile modulus of carbon fibers in both the two outermost CFRP layers is 200 GPa to 600 GPa;

both the two skin layers have a one-dimensionally reinforced CFRP layer containing carbon fibers oriented in an angle range from $+75^{\circ}$ to $+90^{\circ}$ with respect to the reference direction and having a tensile modulus 1.5 times to 3.0 times that of carbon fibers of the outermost CFRP layer contained in the skin layer, and/or a one-dimensionally reinforced CFRP layer containing carbon fibers oriented in an angle range from -75° to -90° with respect to the reference direction and having a tensile modulus 1.5 times to 3.0 times that of carbon fibers of the outermost CFRP layer contained in the skin layer;

said core layer has a one-dimensionally reinforced CFRP layer containing carbon fibers oriented in an angle range from -20° to $+20^{\circ}$ with respect to the reference direction and having a tensile modulus of 200 GPa to 400 GPa; and

said core layer also has a one-dimensionally reinforced CFRP layer containing carbon fibers oriented in an angle range from $+75^{\circ}$ to $+90^{\circ}$ with respect to the reference direction and having a tensile modulus of 200 GPa to 400 GPa and/or a one-dimensionally reinforced CFRP layer containing carbon fibers oriented in an angle range from -75° to -90° with respect to the reference direction and having a tensile modulus of 200 GPa to 400 GPa.

10 (original): The dummy wafer according to claim 9, wherein at least one of said two skin layers further has a one-dimensionally reinforced CFRP layer containing carbon fibers oriented in an angle range from $+30^{\circ}$ to $+60^{\circ}$ with respect to the reference direction and having a tensile modulus 1.5 times to 3.0 times that of carbon fibers of the outermost CFRP layer contained in the skin layer, and/or a one-dimensionally reinforced CFRP layer containing carbon fibers oriented in an angle range from -30° to -60° with respect to the reference direction and having a tensile modulus 1.5 times to 3.0 times that of carbon fibers of the outermost CFRP layer contained in the skin layer.

11 (previously presented): The dummy wafer according to claim 6 further comprising a carbon fiber cloth layer on each of the principal surfaces.

12 (currently amended): The dummy wafer comprising a carbon fiber reinforced plastic~~The dummy wafer according to claim 1,~~ wherein the matrix resin contained in said carbon fiber reinforced plastic contains an epoxy resin composition that contains diaminodiphenylsulfone as a curing agent.

13 (currently amended): A dummy wafer comprising a carbon fiber reinforced plastic, having a wafer substrate including a carbon fiber reinforced plastic~~The dummy wafer according to claim 2,~~ wherein

said wafer substrate has a processed surface, and
has a coating layer that coats said processed surface and consists of a resin that has resistance against polar solvent and cures at a temperature of 70°C or lower.

14 (previously presented): The dummy wafer according to claim 9 further comprising a carbon fiber cloth layer on each of the principal surfaces.

15 (previously presented): The dummy wafer according to claim 9, wherein the matrix resin contained in said carbon fiber reinforced plastic contains an epoxy resin composition that contains diaminodiphenylsulfone as a curing agent.

16 (previously presented): The dummy wafer according to claim 9, wherein
said wafer substrate has a processed surface, and
has a coating layer that coats said processed surface and consists of a resin that has resistance against polar solvent and cures at a temperature of 70°C or lower.

17 (previously presented): A dummy wafer substrate comprising:

an upper skin layer comprising an outermost layer and another layer, each composed of a cured unidirectional prepreg sheet made of a one-dimensionally reinforced CFRP including oriented carbon fibers, wherein the carbon fibers of the outermost layer and those of the other layer are oriented in different angles, and the other layer has a higher tensile strength than that of the outermost layer;

a lower skin layer comprising an outermost layer and another layer, each composed of a cured unidirectional prepreg sheet made of a one-dimensionally reinforced CFRP including oriented carbon fibers, wherein the carbon fibers of the outermost layer and those of the other layer are oriented in different angles, and the other layer has a higher tensile strength than that of the outermost layer; and

a core layer interposed between the upper skin layer and the lower skin layer, said core layer made of one-dimensionally reinforced CFRP including oriented carbon fibers.

18 (previously presented): The dummy wafer according to claim 17, wherein the outermost layer and the other layer of the upper skin layer have tensile strength of 200-600 GPa and 400-1000 GPa, respectively.

19 (previously presented): The dummy wafer according to claim 17, wherein the outermost layer and the other layer of the lower skin layer have a tensile strength of 200-600 GPa and 400-1000 GPa, respectively.

20 (previously presented): The dummy wafer according to claim 17, which has a thickness of 0.5-0.8 mm, wherein the upper and lower skin layers each have a thickness which is 10% to 45% of that of the dummy wafer.